

MULTILAYER	
CERTIFICATION	UL: E171525 / ISO 9001 / ISO 14001 / TS 16949
BASE MATERIALS	FR4
SURFACE FINISHES	HASL, Immersion Gold ENTEK, Immersion Siler, Immersion Tin, Flash Gold Plating, Hard Gold, Finger Plating.
TECHNICAL CAPABILITY	PCB Thickness : 0.4 to 3.2mm Inner Layer : 4/4 mils (0.08mm) Outer Layer : 4/4 mils (0.08mm) SMD Pitch : min 16 mils (0.4mm) Min. Finished Vias : min 8 mils (0.20mm) by drill Min Vias : 8 mils (0.20mm) Aspect Ratio : 7:1